TOREX

Torex...Powerfully Small!

TOREX SEMICONDUCTOR LTD.
Quality Assurance Dept.

Composition Table

Product(Pb-free): XCL208xxxxDR
Typical mass: 16.5 mg

Part	Part name	Weight(mg)	Material name	Ratio(ppm)	CAS №
Coil	Core（Ferrite）	3.650	Iron oxide	221200	1309-37-1
		0.800	Zinc oxide	48500	1314-13-2
		0.660	Nickel oxide	40000	1313-99-1
		0.200	Copper oxide	12100	1317-38-0
		0.030	Tin oxide	1800	18282-10-5
	Internal conductor	0.210	Silver	12700	7440-22-4
	Plating	0.250	Silver	15200	7440-22-4
		0.050	Nickel	3000	7440-02-0
		0.150	Tin	9100	7440-31-5
Pb-free solder	Pb-free solder	0.913	Tin	55300	7440-31-5
		0.048	Antimony	2900	7440-36-0
IC	Silicon chip	0.666	Silicon	40400	7440-21-3
		-	Arsenic	<1	7440-38-2
	Lead pad	0.906	Nickel	54900	7440-02-0
		0.086	Silver	5200	7440-22-4
		0.010	Gold	600	7440-57-5
	Die attach	0.218	Silica	13200	60676-86-0
		0.141	Bismaleimide resin	8600	-
		0.054	Acrylic resin	3300	-
		0.039	Epoxy resin	2300	-
	Bonding wire	0.071	Gold	4300	7440-57-5
	Resin	6.588	Silica	399300	60676-86-0
		0.349	Epoxy resin	21100	-
		0.233	Phenol resin	14100	-
		0.155	Metal hydoxide	9400	-
		0.023	Silica, crystalline	1400	14808-60-7

* The component composition is based on the information provided by raw material vender.

* The mass of the IC and its fractions could be different due to the manufacturing conditions of materials.

* Any indication "-" in CAS number means "confidential."